

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JOHN JHY LIAW	10/16/2013
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. 6	
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14062993
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	24061.2664	
NAME OF SUBMITTER:	DENISE M. WILSON	
SIGNATURE:	/Denise M. Wilson/	
DATE SIGNED:	03/18/2014	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS, we,

(1) John Jhy Liaw of No. 15, Lane 447, Xuefu E. Road
Zhudong Township
Hsinchu County 310, Taiwan, R.O.C.

have invented certain improvements in

GATE DEVICE OVER STRAINED FIN STRUCTURE

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
X filed on October 25, 2013, and assigned application number 14/062,993; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2013-1154/24061.2664
Customer No.: 000042717

Inventor Name: John Jhy Liaw

Residence Address: No. 15, Lane 447, Xuefu E. Road, Zhudong Township
Hsinchu County 310 Taiwan, R.O.C.

Dated: Oct. 16, 2013

John Jhy Liaw
Inventor Signature
